



Materials Declaration

Package	CSP-BGA - Stacked Die
Body Size	9 X 9
Ball Count	124
Option	Pb-Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	88	8.94 E-02	464810
Epoxy Resin	12	1.22 E-02	63431

Laminate			
Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	42.3	1.67 E-02	86827
Copper	23.8	9.40 E-03	48873
Gold	1.5	6.00 E-04	3120
Nickel	9.1	3.60 E-03	18717
Solder Mask	20.5	8.10 E-03	42114
Brominated Compound	2.89	1.10 E-03	5719

Solder Ball			
Item	% of Balls	Weight (g)	PPM
Sn	96.5	3.15 E-02	163775
Ag	3	1.00 E-03	5199
Cu	0.5	2.00 E-04	1040

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	2.09 E-03	10844

Chip 1- Bottom			
Item	% of Chip	Weight (g)	PPM
Si	100	8.06 E-03	41898

Chip 2 - Top			
Item	% of Chip	Weight (g)	PPM
Si	100	6.17 E-03	32092

Die Attach 1 - Bottom Die			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	78	1.00 E-03	5199
Resin	22	3.00 E-04	1560

Die Attach 2 - Top Die			
Item	% of Die Attach	Weight (g)	PPM
Si Filler	6	2.00 E-05	104
Epoxy/Acrylic	94	3.00 E-04	1560

Film Spacer			
Item	% of Spacer	Weight (g)	PPM
Epoxy	60	3.00 E-04	1560
Rubber	30	2.00 E-04	1040
Silica	10	1.00 E-04	520

Package Totals

Weight (g)	PPM
1.92 E-01	1000000

Molding Compound		
Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Laminate		
Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Die Attach Paste 1		
Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Die Attach Paste 2		
Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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1/2/2006

